MMBF0201NL, MVMBF0201NL

Power MOSFET 300 mAmps, 20 Volts

N-Channel SOT-23

These miniature surface mount MOSFETs low RDS(on) assure minimal power loss and conserve energy, making these devices ideal for use in small power management circuitry. Typical applications are dc-dc converters, power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

Features

- Low R_{DS(on)} Provides Higher Efficiency and Extends Battery Life
- Miniature SOT-23 Surface Mount Package Saves Board Space
- MVMBF Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	20	Vdc
Gate-to-Source Voltage - Continuous	V _{GS}	± 20	Vdc
$ \begin{array}{l} \text{Drain Current} \\ - \text{ Continuous } @ \ T_A = 25^\circ\text{C} \\ - \text{ Continuous } @ \ T_A = 70^\circ\text{C} \\ - \text{ Pulsed Drain Current } (t_p \leq 10 \ \mu\text{s}) \end{array} $	I _D I _D I _{DM}	300 240 750	mAdc
Total Power Dissipation @ $T_A = 25^{\circ}C$	PD	225	mW
Operating and Storage Temperature Range	T _J , T _{stg}	– 55 to 150	°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	ΤL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

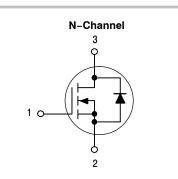


ON Semiconductor®

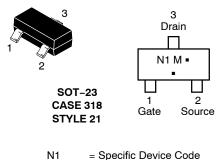
http://onsemi.com

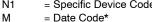
300 mAMPS - 20 VOLTS

 $R_{DS(on)} = 1 \Omega$



MARKING DIAGRAM AND PIN ASSIGNMENT





= Date Code*

= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBF0201NLT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
MVMBF0201NLT1G*	SOT-23 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBF0201NL, MVMBF0201NL

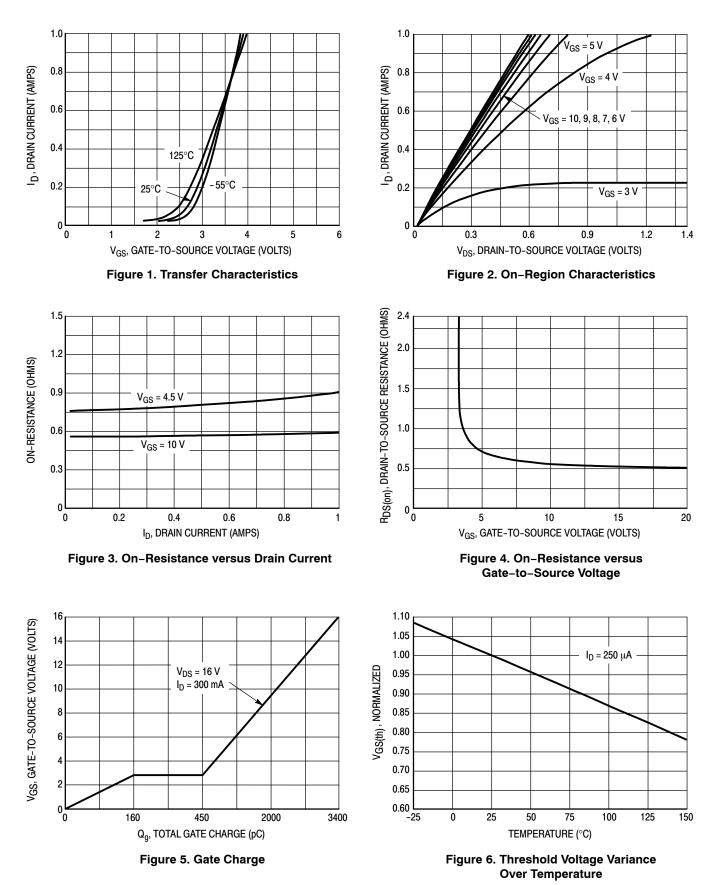
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Cha	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS			•			
Drain-to-Source Breakdown Voltag (V _{GS} = 0 Vdc, I _D = 10 μA)	V _{(BR)DSS}	20	-	-	Vdc	
Zero Gate Voltage Drain Current ($V_{DS} = 16$ Vdc, $V_{GS} = 0$ Vdc) ($V_{DS} = 16$ Vdc, $V_{GS} = 0$ Vdc, T					1.0 10	μAdc
Gate-Body Leakage Current (V _{GS}	= ± 20 Vdc, V _{DS} = 0)	I _{GSS}	-	_	±100	nAdc
ON CHARACTERISTICS (Note 1)			•			
Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 250 μAdc)	V _{GS(th)}	1.0	1.7	2.4	Vdc	
$\begin{array}{l} \mbox{Static Drain-to-Source On-Resista} \\ (V_{GS} = 10 \mbox{ Vdc}, \mbox{ I}_{D} = 300 \mbox{ mAdc}) \\ (V_{GS} = 4.5 \mbox{ Vdc}, \mbox{ I}_{D} = 100 \mbox{ mAdc}) \end{array}$	r _{DS(on)}		0.75 1.0	1.0 1.4	Ω	
Forward Transconductance (V _{DS} =	9 _{FS}	-	450	_	mMhos	
DYNAMIC CHARACTERISTICS			•			
Input Capacitance	(V _{DS} = 5.0 V)	C _{iss}	-	45	_	pF
Output Capacitance	(V _{DS} = 5.0 V)	C _{oss}	-	25	_	
Transfer Capacitance	(V _{DG} = 5.0 V)	C _{rss}	-	5.0	_	
SWITCHING CHARACTERISTICS	(Note 2)		•			
Turn-On Delay Time		t _{d(on)}	-	2.5	-	ns
Rise Time	(V _{DD} = 15 Vdc, I _D = 300 mAdc,	t _r	-	2.5	-	
Turn-Off Delay Time	R _L = 50 Ω)	t _{d(off)}	-	15	-	
Fall Time	_	t _f	-	0.8	-	
Gate Charge (See Figure 5)	QT	-	1400	-	рС	
SOURCE-DRAIN DIODE CHARAG	CTERISTICS			•		
Continuous Current	ا _S	-	-	0.3	Α	
Pulsed Current	I _{SM}	-	-	0.75		
Forward Voltage (Note 2)	V _{SD}	-	0.85	_	V	

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
Switching characteristics are independent of operating junction temperature.

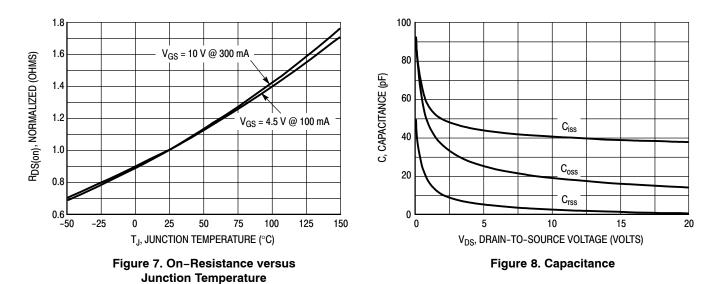
MMBF0201NL, MVMBF0201NL

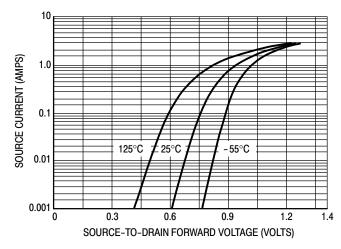
TYPICAL ELECTRICAL CHARACTERISTICS



MMBF0201NL, MVMBF0201NL

TYPICAL ELECTRICAL CHARACTERISTICS

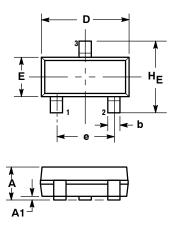


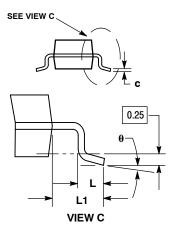




PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH.

 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

1 HICKNESS OF BASE MATERIAL. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, DOOTDISIONS OF CATE PURDED

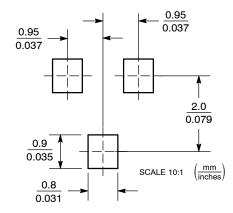
PROI	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 21: PIN 1. GATE

2. SOURCE

3. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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